

Title (en)  
Punching apparatus and punching method

Title (de)  
Vorrichtung sowie Verfahren zum Stanzen

Title (fr)  
Dispositif ainsi que procédé de poinçonnage

Publication  
**EP 1101580 A3 20021211 (EN)**

Application  
**EP 00125144 A 20001117**

Priority  
JP 32712699 A 19991117

Abstract (en)  
[origin: EP1101580A2] In a stamping apparatus, a subtracter 22b and an adder 23b compare an output value of an amplifier 29 which is a signal proportional to  $\dot{A}T\ddot{U}$  expressing the torque generated at a fulcrum 101 by the reaction force  $\ddot{A}F\ddot{U}$  from the material to be stamped 6, to a pulse . duty setting value stored in a pulse . duty setting section 21b, and a signal in which the difference is added to the pulse . duty setting value, is generated, and a switch 25 inputs the signal into a comparator 24b in order to make the signal the comparison signal to the chopping wave outputted from a chopping wave generation circuit 26' in the PWM pulse generation circuit 26. <IMAGE>

IPC 1-7  
**B26F 1/02**; B26F 1/24; B26D 5/00; B26D 5/16; B44B 5/00; B44B 3/00; B26D 5/12

IPC 8 full level  
**B44B 5/00** (2006.01)

CPC (source: EP)  
**B44B 5/0066** (2013.01)

Citation (search report)

- [A] DE 3932549 A1 19900405 - ANDO ELECTRIC [JP]
- [PA] EP 0982152 A2 20000301 - ANDO ELECTRIC [JP]
- [A] US 5628673 A 19970513 - MOROOKA MASAYA [JP]
- [A] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 12 31 October 1998 (1998-10-31)

Cited by  
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